

Date: - 26 July, 2005

Data Sheet Issue:-1

## **Provisional Data**

# Asymmetric Thyristor Types A1237NC200 to A1237NC280

Development Type No.: AX146NC280

## **Absolute Maximum Ratings**

	VOLTAGE RATINGS	7	MAXIMUM LIMITS	UNITS
$V_{DRM}$	Repetitive peak off-state voltage, (note 1)		2800	V
$V_{DSM}$	Non-repetitive peak off-state voltage, (note 1)		2800	V
$V_{RRM}$	Repetitive peak reverse voltage, (note 1)		30	V
$V_{RSM}$	Non-repetitive peak reverse voltage, (note 1)		30	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I <sub>T(AV)M</sub>	Maximum average on-state current, T <sub>sink</sub> =55°C, (note 2)	1237	А
$I_{T(AV)M}$	Maximum average on-state current. T <sub>sink</sub> =85°C, (note 2)	785	Α
$I_{T(AV)M}$	Maximum average on-state current. T <sub>sink</sub> =85°C, (note 3)	430	Α
I <sub>T(RMS)M</sub>	Nominal RMS on-state current, Tsink=25°C, (note 2)	2555	Α
I <sub>T(d.c.)</sub>	D.C. on-state current, T <sub>sink</sub> =25°C, (note 4)	1962	Α
I <sub>TSM2</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>rm</sub> ≤10V, (note 5)	18	kA
I <sup>2</sup> t	I <sup>2</sup> t capacity for fusing t/₂=10ms, V <sub>rm</sub> ≤10V, (note 5)	1.62×10 <sup>6</sup>	$A^2s$
(-1: (-14)	Critical rate of rise of on-state current (non-repetitive), (Note 6)	2000	A/µs
(di/dt) <sub>cr</sub>	Critical rate of rise of on-state current (repetitive), (Note 6)	1000	A/µs
$V_{RGM}$	Peak reverse gate voltage	10	V
P <sub>G(AV)</sub>	Mean forward-gate power	10	W
P <sub>GM</sub>	Peak forward-gate power	30	W
T <sub>j op</sub>	Operating temperature range	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range	-40 to +150	°C

#### Notes:

- 1) De-rating factor of 0.13% per °C is applicable for T<sub>i</sub> below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- A) Double side cooled.
- 5) Half-sinewave, 125°C T<sub>j</sub> initial.
- 6)  $V_D = 67\% / V_{DRM}$ ,  $I_{FG} = 2A$ ,  $t_r \le 0.5 \mu s$ ,  $T_{case} = 125^{\circ}C$ .



## **Characteristics**

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
.,	NA	-	-	2.1	I <sub>TM</sub> =2000A	V
V <sub>TM</sub>	Maximum peak on-state voltage	-	-	2.7	I <sub>TM</sub> =4500A	V
V <sub>T0</sub>	Threshold voltage	-	-	1.707		V
r <sub>T</sub>	Slope resistance	_	-	0.212		mΩ
(dv/dt) <sub>cr</sub>	Critical rate of rise of off-state voltage	3000	-	-	V <sub>D</sub> =80% V <sub>DRM</sub> , linear ramp, gate o/c	V/µs
I <sub>DRM</sub>	Peak off-state current	_	-	60	Rated V <sub>DRM</sub>	mA
I <sub>RRM</sub>	Peak reverse current	_	-	60	Rated VDRM	mA
V <sub>GT</sub>	Gate trigger voltage	-	-	3.0/	* 05°0	V
I <sub>GT</sub>	Gate trigger current	_	-	400 (	$T_{j}$ =25°C $V_{D}$ =10V, $I_{T}$ =3A	mA
$V_{GD}$	Gate non-trigger voltage	-	-	0.25	Rated V <sub>DRM</sub>	V
Ін	Holding current	-	-	1000	T <sub>j</sub> =25°C	mA
t <sub>gd</sub>	Gate-controlled turn-on delay time	-	0.9	2.0	V <sub>D</sub> =90% V <sub>DRM</sub> , I <sub>T</sub> =6000A, di/dt=1500A/µs,	μs
<b>t</b> gt	Turn-on time	_	1.5	3.0	I <sub>FG</sub> =2A, t <sub>r</sub> =0.5μs, T <sub>j</sub> =25°C	μs
	Town off time	-	25/	$\overline{}$	I <sub>TM</sub> =1000A, t <sub>p</sub> =2000μs, di/dt=60A/μs, V <sub>r</sub> =10V, V <sub>dr</sub> =80%V <sub>DRM</sub> , dV <sub>dr</sub> /dt=20V/μs	
tq	Turn-off time	-	30	1//	$I_{TM}$ =1000A, $t_p$ =2000 $\mu$ s, $di/dt$ =60A/ $\mu$ s, $V_r$ =10V, $V_{dr}$ =80% $V_{DRM}$ , $dV_{dr}/dt$ =200V/ $\mu$ s	μs
	The small reciptor as it is at the boots in le	-	7	0.024	Double side cooled	K/W
$R_{thJK}$	Thermal resistance, junction to heatsink	- /	<u> </u>	^Q.048	Single side cooled	K/W
F	Mounting force	19	( - )	26	(See note 2)	kN
$W_t$	Weight	\	510	/ -		g

Notes:-

1) Unless otherwise indicated T<sub>j</sub>=125°C.

2) For all other mounting forces, please consult factory.





#### **Notes on Ratings and Characteristics**

## 1.0 Voltage Grade Table

Voltage Grade	$egin{array}{c} V_{DRM} \ V \end{array}$	$V_{RRM}$	V <sub>D</sub> DC V
20	2000	30	1250 /
22	2200	30	1350
24	2400	30	1450
26	2600	30	1550
28	2800	30	/ 1650

#### 2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

#### 3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for  $T_i$  below 25°C.

#### 4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

#### 5.0 Snubber Components

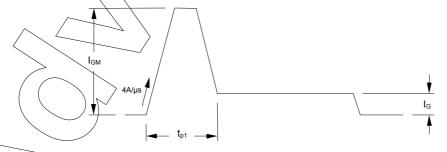
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

## 6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 2000A/µs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 1000A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

#### 7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of  $I_{GM}$  should be between five and ten times  $I_{GT}$ , which is shown on page 3. Its duration  $(t_{pq})$  should be 20 $\mu$ s or sufficient to allow the anode current to reach ten times  $I_L$ , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current  $I_G$  should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times  $I_{GT}$ .

#### 8.0 Computer Modelling Parameters

## 8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{{V_{T0}}^2 + 4 \cdot ff^2 \cdot r_T \cdot W_{AV}}}{2 \cdot ff^2 \cdot r_T}$$

Where  $V_{T0}$ =1.707,  $r_{T}$ =0.212 $m\Omega$ ,

 $R_{\it th}$  = Supplementary thermal impedance, see table below and ff = Form factor, see table below.

Supplementary Thermal Impedance								
Conduction Angle	30°	60°	90° /	120°	\180°	270°	d.c.	
Square wave Double Side Cooled	0.0293	0.0285	0.0278	0.0271	0.0261	0.0249	0.024	
Square wave Single Side Cooled	0.0534	0.053	0.0524	0.0518	0.0509	0.0497	0.0489	
Sine wave Double Side Cooled	0.0286	0.0276	0.0269	0.0263	0.0248			
Sine wave Single Side Cooled	0.0531	0.0523	0.0517	0.0511	0.0497			

Form Factors									
Conduction Angle	30°	60°	90%	/120°	180°	270°	d.c.		
Square wave	3.46	2.45	2	1.73	1.41	1.15	1		
Sine wave	3.98	2.78	2.22	1.88	1.57				

# 8.2 Calculating V<sub>T</sub> using ABCD Coefficients

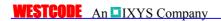
The on-state characteristic I<sub>T</sub> vs. V<sub>T</sub>, on page 6 is represented in two ways;

- the well established  $V_{T0}$  and  $\Gamma_T$  tangent used for rating purposes and a set of constants A, B, C, D, forming the coefficients of the representative equation for  $V_T$  in (ii) terms of I<sub>T</sub> given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V<sub>T</sub> agree with the true device characteristic over a current range, which is limited to that plotted.

,				
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		25°C Coefficients		125°C Coefficients
	A	0.415411291	Α	1.553894527
	B	0.529844	В	0.1270671
	c	4.9×10 <sup>-4</sup>	C	4.73466 ×10 <sup>-4</sup>
_	D	-0.065645	D	-0.03055924
	7			



# 8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$

Where p = 1 to n, n is the number of terms in the series and:

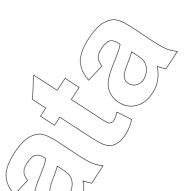
t = Duration of heating pulse in seconds.

 $r_{t}$  = Thermal resistance at time t.

 $r_p$  = Amplitude of  $p_{th}$  term.

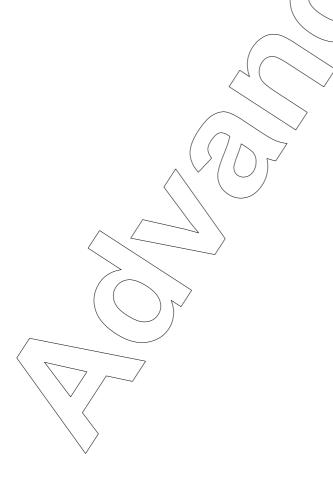
 $\tau_p$  = Time Constant of  $r_{th}$  term.

The coefficients for this device are shown in the tables below:



		D.C. Dou	ble Side Cooled			
Term	1	2	3	<b>A</b> /		5
$r_p$	0.01249139	6.316833×10 <sup>-3</sup>	1.850855×10 <sup>-3</sup>	1.922045×	10 <sup>-3</sup>	6.135330×10 <sup>-4</sup>
$ au_{ ho}$	0.8840810	0.1215195	0.03400152	6.742908×	10 <sup>-3</sup>	1.326292×10 <sup>-3</sup>

	D.C. Single Side Cooled									
Term	1	2	3 ( // ) 4	5	6					
$r_{p}$	0.02919832	4.863568×10 <sup>-3</sup>	3.744798×10 <sup>-3</sup> 6.818034×10 <sup>-3</sup>	2.183558×10 <sup>-3</sup>	1.848294×10 <sup>-3</sup>					
$ au_{ ho}$	6.298105	3.286174	0,5359179 0.1186897	0.02404574	3.379476×10 <sup>-3</sup>					



## **Curves**

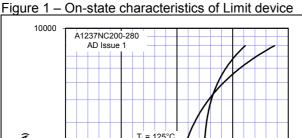
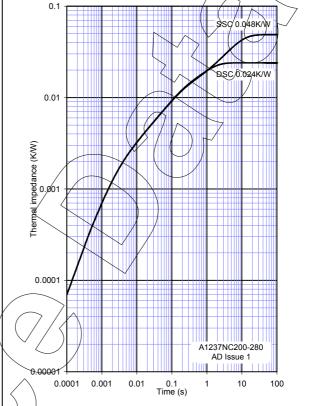
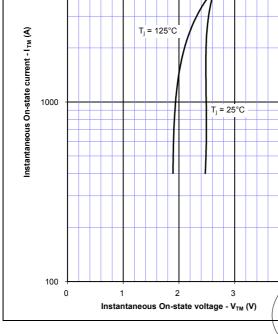


Figure 2 – Transient thermal impedance





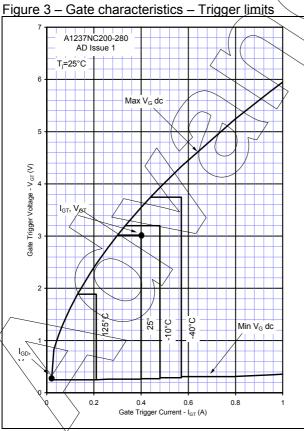


Figure 4 – Gate characteristics – Power curves

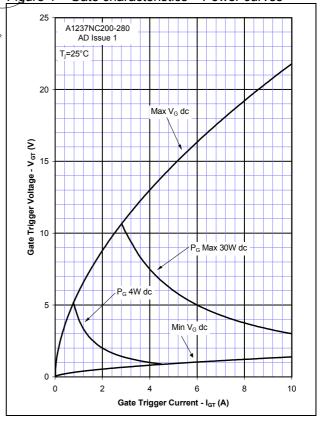


Figure 5 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

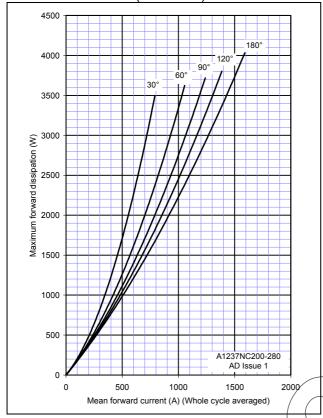


Figure 7 – On-state current vs. Power dissipation - Double Side Cooled (Square wave)

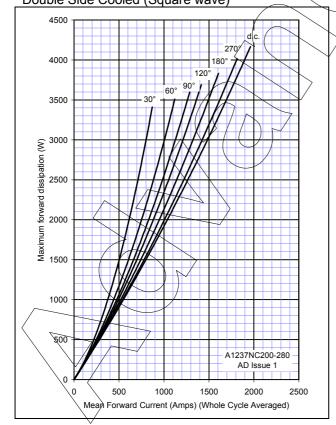


Figure 6 – On-state current vs. Heatsink temperature – Double Side Cooled (Sine wave)

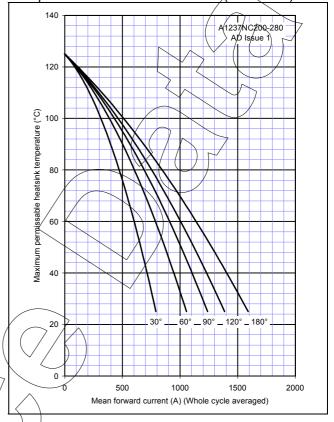


Figure 8 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)

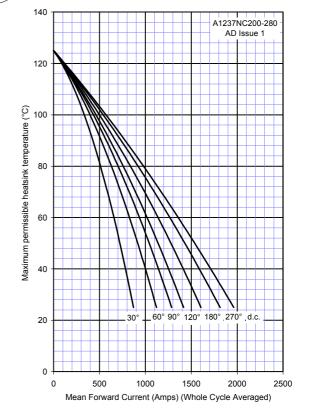


Figure 9 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

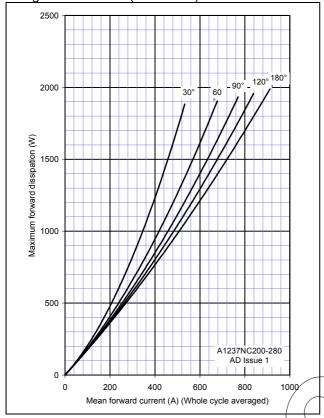


Figure 11 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

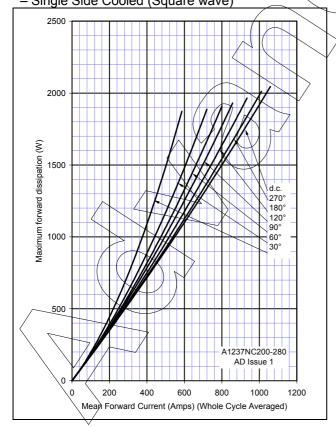


Figure 10 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine-wave)

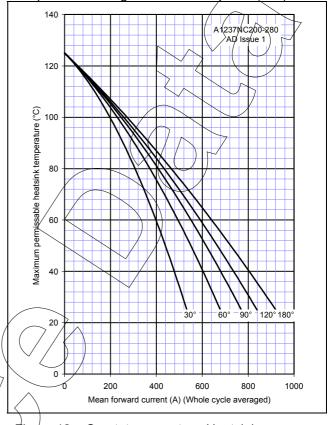
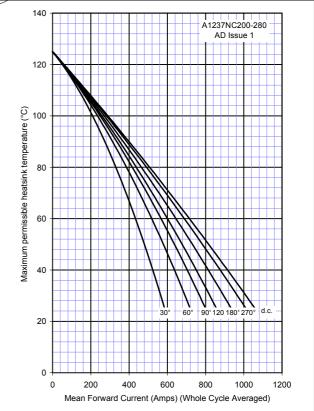
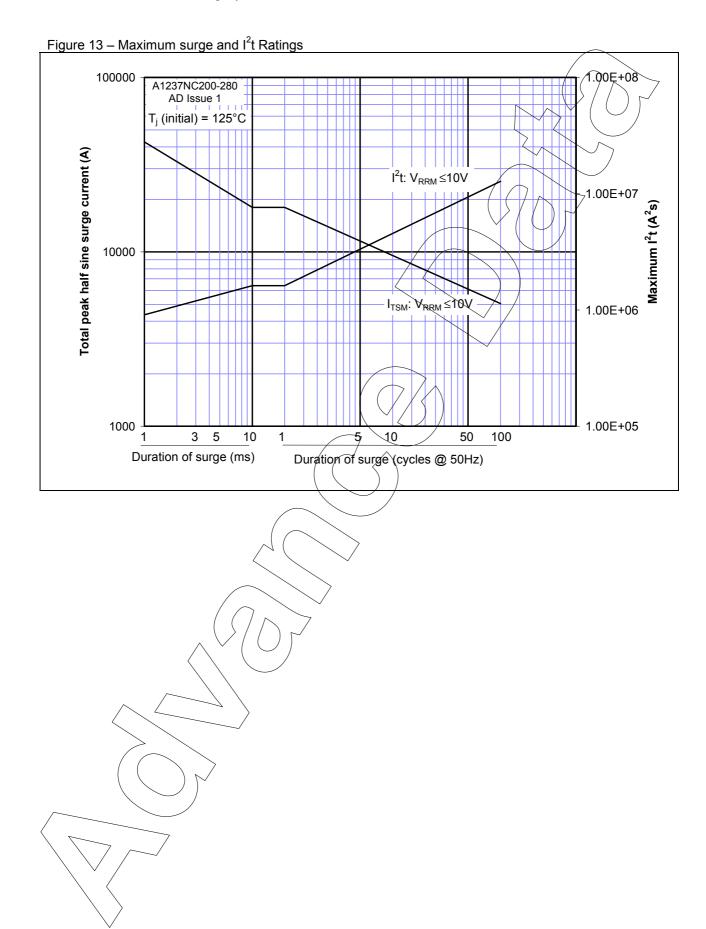


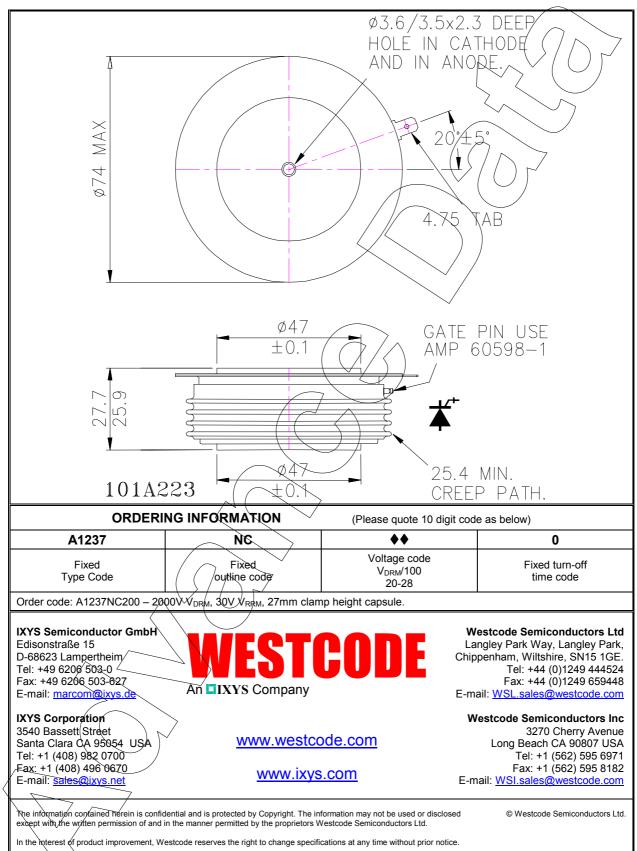
Figure 12 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)







#### **Outline Drawing & Ordering Information**



Devices with a suffix code (2-letter, 3-letter or letter/digit/letter combination) added to their generic code are not necessarily subject to the conditions and limits contained in this report.